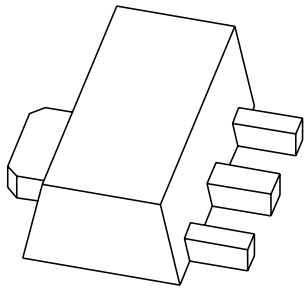


# DATA SHEET



## **BF621; BF623** PNP high-voltage transistors

Product specification  
Supersedes data of 1999 Apr 21

2004 Dec 14

# PNP high-voltage transistors

# BF621; BF623

### FEATURES

- Low current (max. 50 mA)
- High voltage (max. 300 V).

### APPLICATIONS

- Video output stages.

### DESCRIPTION

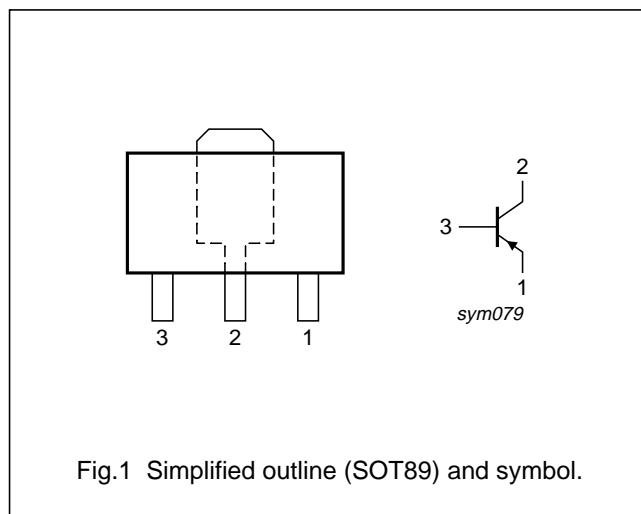
PNP high-voltage transistor in a SOT89 plastic package.  
NPN complements: BF620 and BF622.

### MARKING

TYPE NUMBER	MARKING CODE
BF621	DF
BF623	DB

### PINNING

PIN	DESCRIPTION
1	emitter
2	collector
3	base



### ORDERING INFORMATION

TYPE NUMBER	PACKAGE		
	NAME	DESCRIPTION	VERSION
BF621	SC-62	plastic surface mounted package; collector pad for good heat transfer; 3 leads	SOT89
BF623			

## PNP high-voltage transistors

## BF621; BF623

**LIMITING VALUES**

In accordance with the Absolute Maximum Rating System (IEC 60134).

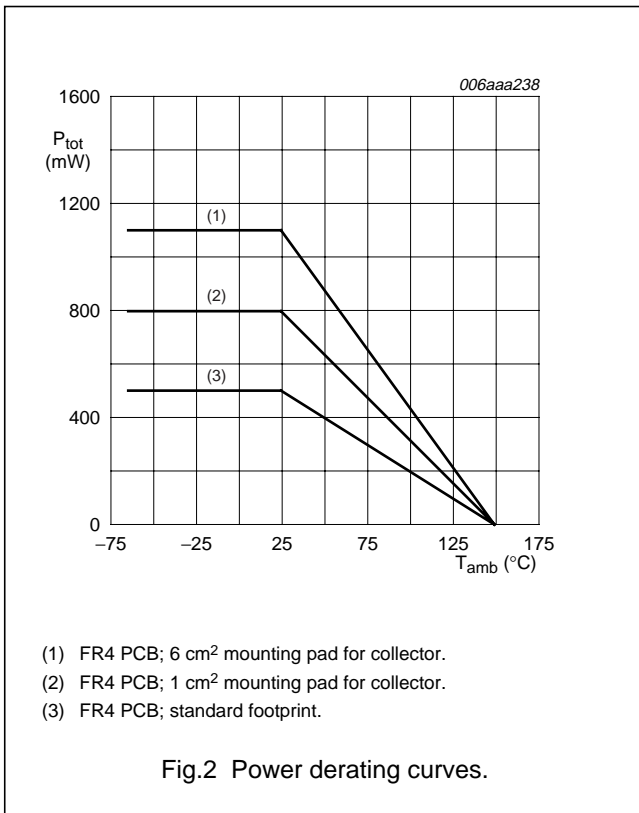
SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
V <sub>CBO</sub>	collector-base voltage	open emitter	–	–300	V
	BF621				
V <sub>CEO</sub>	collector-emitter voltage	open base	–	–300	V
	BF623				
V <sub>EBO</sub>	emitter-base voltage	open collector	–	–5	V
I <sub>C</sub>	collector current (DC)		–	–50	mA
I <sub>CM</sub>	peak collector current		–	–100	mA
I <sub>BM</sub>	peak base current		–	–50	mA
P <sub>tot</sub>	total power dissipation	T <sub>amb</sub> ≤ 25 °C	–	0.5	W
		note 1			
		note 2			
T <sub>stg</sub>	storage temperature		–65	+150	°C
T <sub>j</sub>	junction temperature		–	150	°C
T <sub>amb</sub>	ambient temperature		–65	+150	°C

**Notes**

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated and standard footprint.
2. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.
3. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 6 cm<sup>2</sup>.

PNP high-voltage transistors

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PNP high-voltage transistors

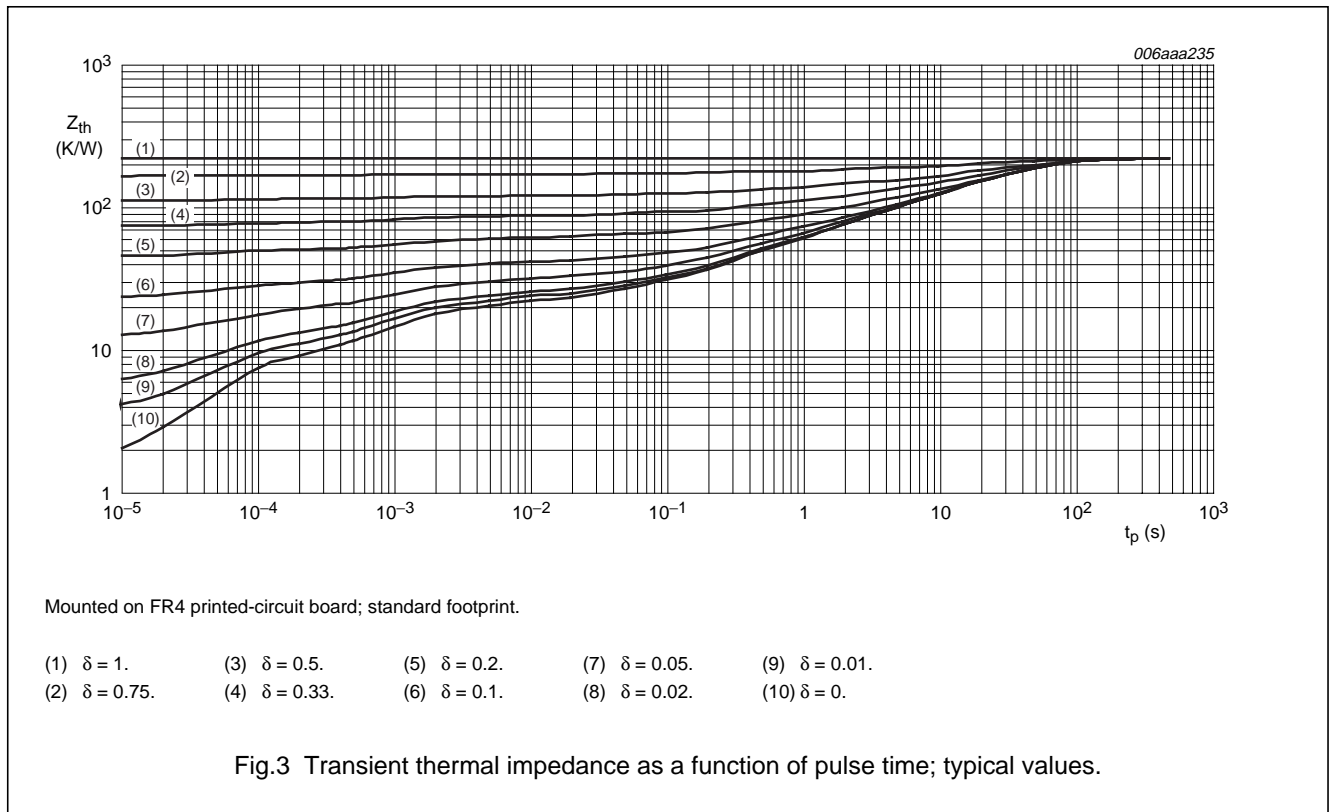
BF621; BF623

**THERMAL CHARACTERISTICS**

SYMBOL	PARAMETER	CONDITIONS	VALUE	UNIT
$R_{th(j-a)}$	thermal resistance from junction to ambient	in free air		
		note 1	250	K/W
		note 2	156	K/W
		note 3	113	K/W
$R_{th(j-s)}$	thermal resistance from junction to soldering point		30	K/W

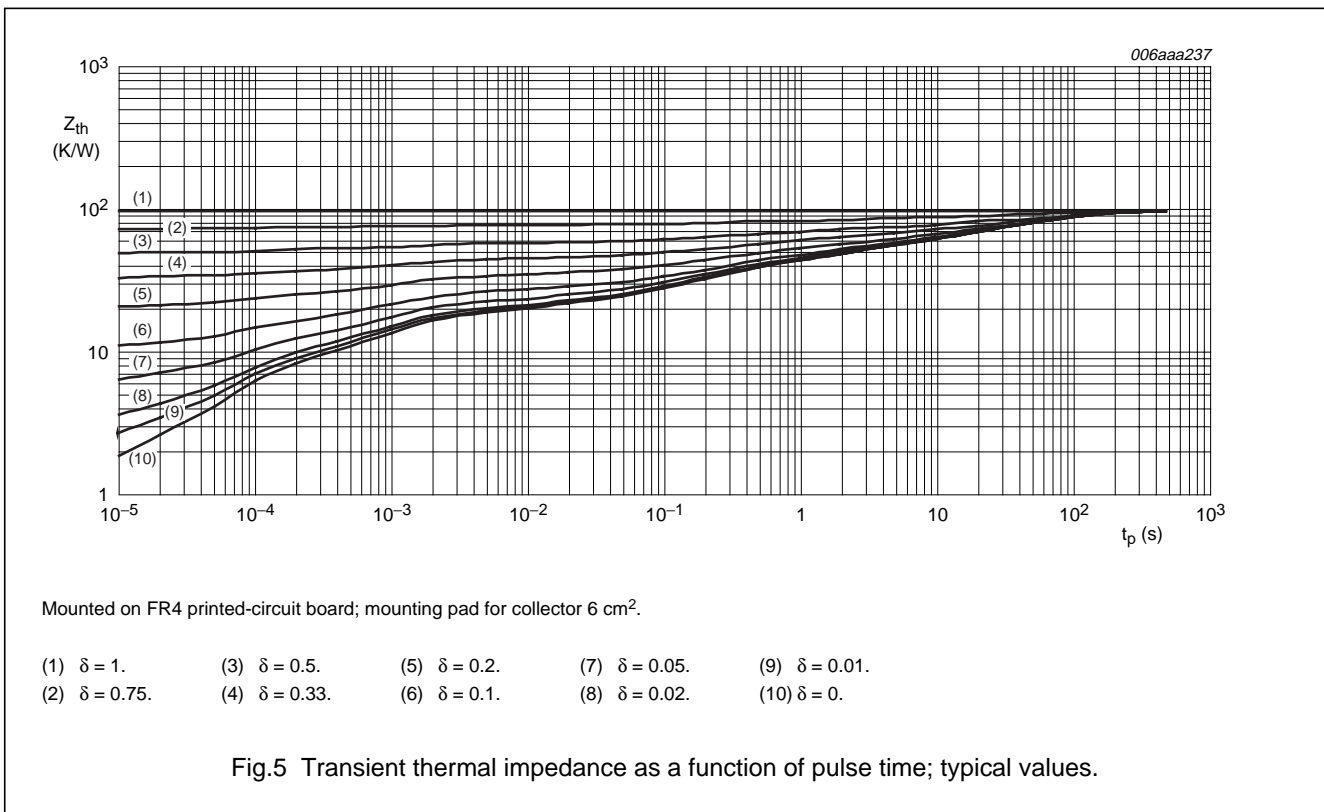
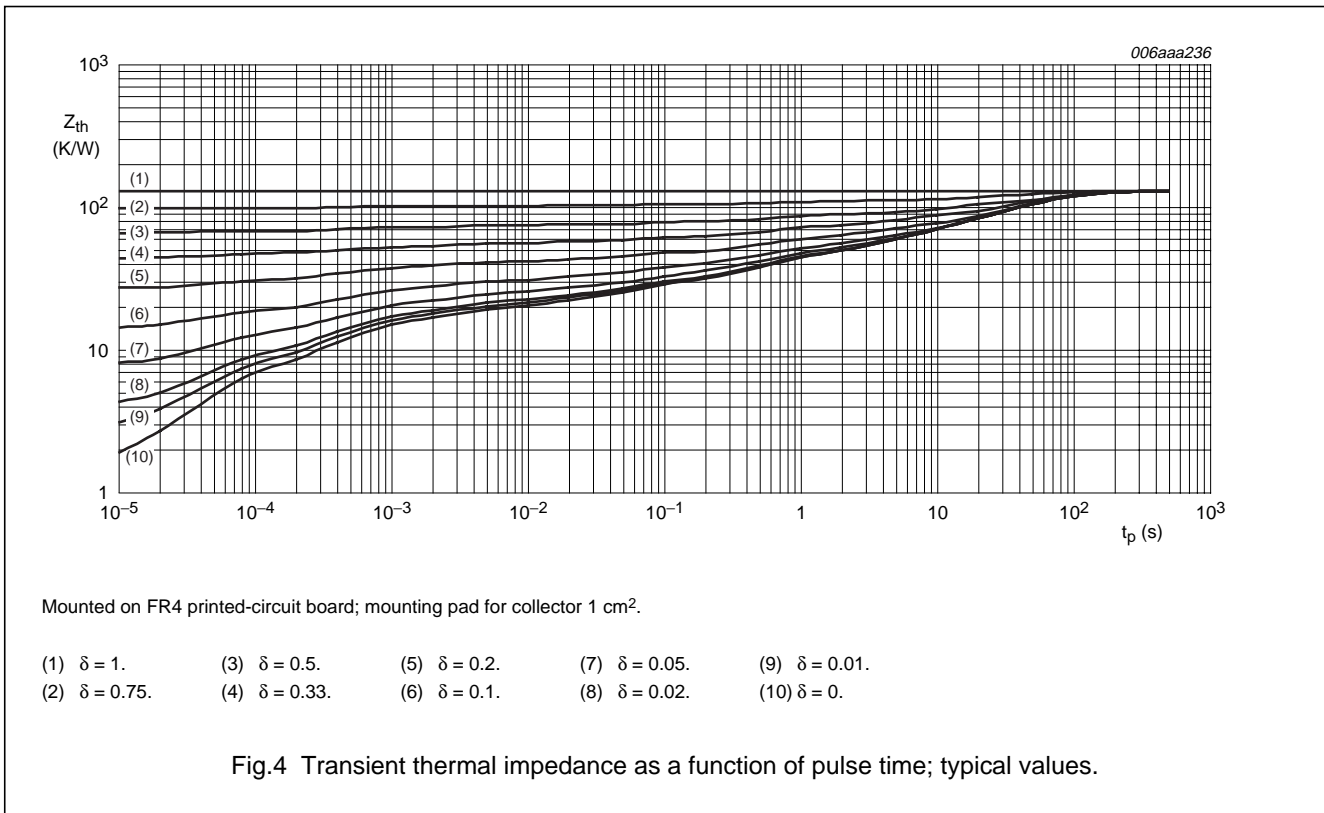
**Notes**

1. Device mounted on a printed-circuit board, single-sided copper, tin-plated and standard footprint.
2. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 1 cm<sup>2</sup>.
3. Device mounted on a printed-circuit board, single-sided copper, tin-plated and mounting pad for collector 6 cm<sup>2</sup>.



PNP high-voltage transistors

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## PNP high-voltage transistors

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**CHARACTERISTICS**

$T_{amb} = 25\text{ °C}$  unless otherwise specified.

SYMBOL	PARAMETER	CONDITIONS	MIN.	MAX.	UNIT
$I_{CBO}$	collector-base cut-off current	$I_E = 0\text{ A}; V_{CB} = -200\text{ V}$	–	–10	nA
		$I_E = 0\text{ A}; V_{CB} = -200\text{ V}; T_j = 150\text{ °C}$	–	–10	$\mu\text{A}$
$I_{EBO}$	emitter-base cut-off current	$I_C = 0\text{ A}; V_{EB} = -5\text{ V}$	–	–50	nA
$h_{FE}$	DC current gain	$I_C = -25\text{ mA}; V_{CE} = -20\text{ V}$	50	–	
$V_{CEsat}$	collector-emitter saturation voltage	$I_C = -30\text{ mA}; I_B = -5\text{ mA}$	–	–800	mV
$C_{re}$	feedback capacitance	$I_C = i_c = 0\text{ A}; V_{CE} = -30\text{ V}; f = 1\text{ MHz}$	–	1.6	pF
$f_T$	transition frequency	$I_C = -10\text{ mA}; V_{CE} = -10\text{ V}; f = 100\text{ MHz}$	60	–	MHz

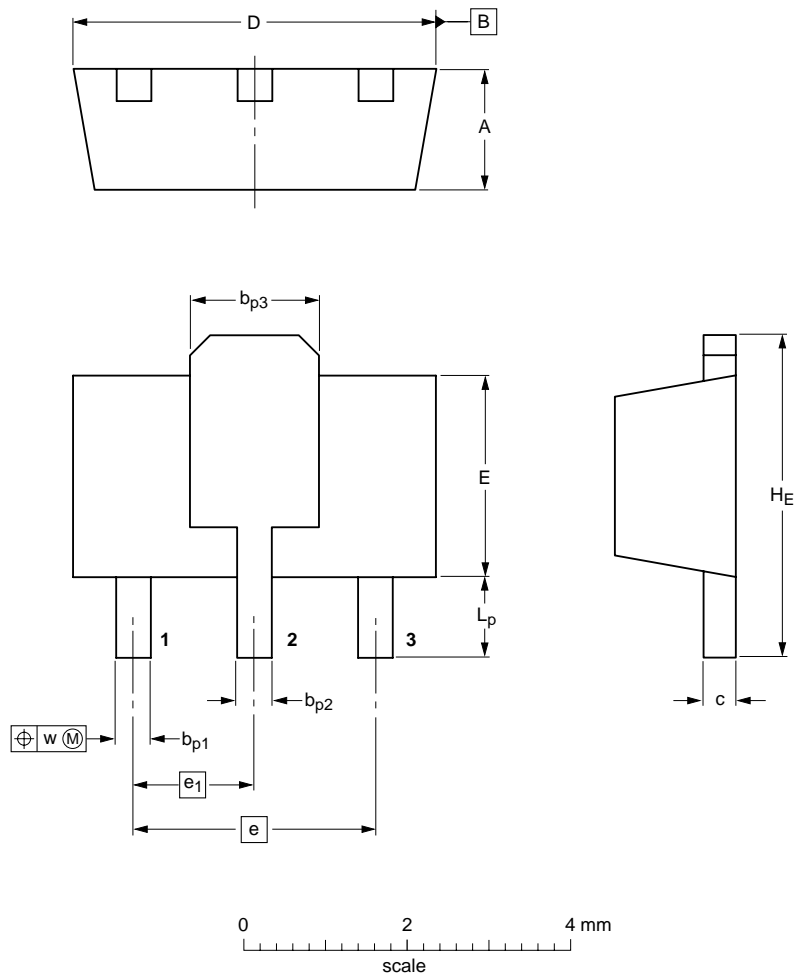
PNP high-voltage transistors

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PACKAGE OUTLINE

Plastic surface mounted package; collector pad for good heat transfer; 3 leads

SOT89



DIMENSIONS (mm are the original dimensions)

UNIT	A	bp1	bp2	bp3	c	D	E	e	e1	HE	Lp	w
mm	1.6 1.4	0.48 0.35	0.53 0.40	1.8 1.4	0.44 0.23	4.6 4.4	2.6 2.4	3.0	1.5	4.25 3.75	1.2 0.8	0.13

OUTLINE VERSION	REFERENCES			EUROPEAN PROJECTION	ISSUE DATE
	IEC	JEDEC	JEITA		
SOT89		TO-243	SC-62		99-09-13 04-08-03



## PNP high-voltage transistors

BF621; BF623

## DATA SHEET STATUS

LEVEL	DATA SHEET STATUS <sup>(1)</sup>	PRODUCT STATUS <sup>(2)(3)</sup>	DEFINITION
I	Objective data	Development	This data sheet contains data from the objective specification for product development. Philips Semiconductors reserves the right to change the specification in any manner without notice.
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